Centrale technologique pour la Recherche Technologique de Base LAAS-CNRS

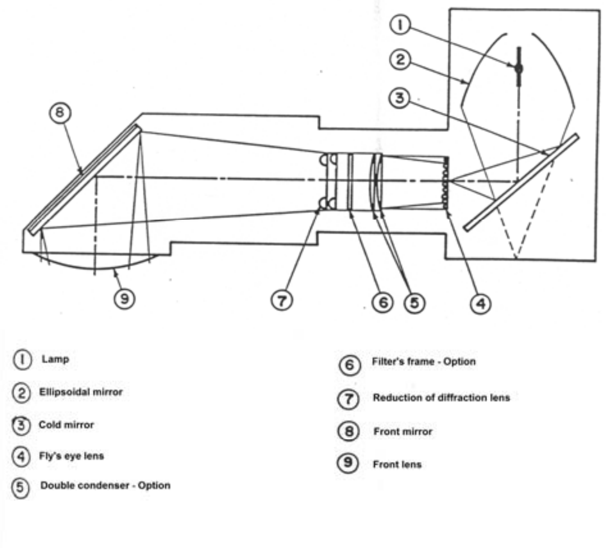
EVG 620 MASK ALIGNER

The EVG 620 enables the transfer of the pattern from a mask to a substrate by irradiating a photosensitive material (ultraviolet sensitive)

MAIN CHARACTERISTICS

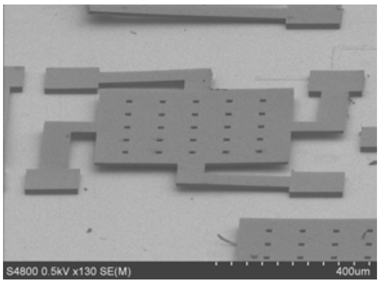
- Mercury vapor lamp
- Substrates diameters from 2 to 6’’
- Automatic alignment
- Double side alignment
- Automated loading by robot
- Wavelength from 320nm to 405nm

OPERATIONS

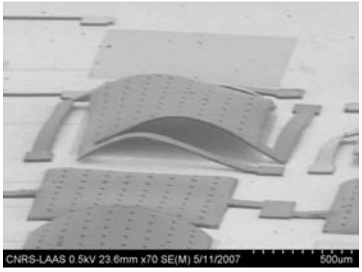


The EVG620 mask aligner enables the insulation of 2 to 6’’ diameter substrates with a 20µm prealignment accuracy. A robot arm does the loading and alignments can be fully automated thanks to pattern recognition functionality of the software. This equipment includes a double side alignment functionality, which means it is possible to align patterns on the backside of the substrate with others on the front side. Insulations is done in proximity, contact or in vacuum chamber.

REALIZATION EXAMPLES



SU8 mirrors



CONTACTS

Veronique Conédéra; conedera@laas.fr
Laurent Mazenq; lmazenq@laas.fr
Fabien Mesnilgrente; fabien.mesnilgrente@laas.fr

VERSION FRANCAISE→